

AD845—SPECIFICATIONS (@ 25°C and ±15 V dc, unless otherwise noted.)

Parameter	Conditions	AD845J/A			AD845K/B			AD845S			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
INPUT OFFSET VOLTAGE ¹											
Initial Offset	T_{MIN} to T_{MAX}		0.7	1.5		0.1	0.25		0.25	1.0	mV
Offset Drift				2.5 20			0.4 5.0			2.0 10	mV μV/°C
INPUT BIAS CURRENT ²											
Initial	$V_{\text{CM}} = 0 \text{ V}$ T_{MIN} to T_{MAX}		0.75	2 45/75		0.5 1 18/38			0.75 2 500		nA nA
INPUT OFFSET CURRENT											
Initial	$V_{\text{CM}} = 0 \text{ V}$ T_{MIN} to T_{MAX}		25	300 3/6.5		15 100 1.2/2.6			25 300 20		pA nA
INPUT CHARACTERISTICS											
Input Resistance			10^{11}			10^{11}			10^{11}		kΩ
Input Capacitance			4.0			4.0			4.0		pF
INPUT VOLTAGE RANGE											
Differential	$V_{\text{CM}} = \pm 10 \text{ V}$		±20			±20			±20		V
Common-Mode		±10	+10.5/−13		±10	+10.5/−13		±10	+10.5/−13		V
Common-Mode Rejection		86	110		94	113		86	110		dB
INPUT VOLTAGE NOISE	0.1 Hz to 10 Hz $f = 10 \text{ Hz}$ $f = 100 \text{ Hz}$ $f = 1 \text{ kHz}$ $f = 10 \text{ kHz}$ $f = 100 \text{ kHz}$		4 80 60 25 18 12			4 80 60 25 18 12			4 80 60 25 18 12		μV p-p nV/√Hz nV/√Hz nV/√Hz nV/√Hz nV/√Hz
INPUT CURRENT NOISE	$f = 1 \text{ kHz}$		0.1			0.1			0.1		pA/√Hz
OPEN-LOOP GAIN	$V_{\text{O}} = \pm 10 \text{ V}$ $R_{\text{LOAD}} \geq 2 \text{ k}\Omega$ $R_{\text{LOAD}} \geq 500 \Omega$ $T_{\text{MIN}} - T_{\text{MAX}}$	200 100 70	500 250		250 125 75	500 250		200 100 50	500 250		V/mV V/mV V/mV
OUTPUT CHARACTERISTICS											
Voltage	$R_{\text{LOAD}} \geq 500 \Omega$	±12.5			±12.5			±12.5			V
Current	Short Circuit		50			50			50		mA
Output Resistance	Open Loop		5			5			5		Ω
FREQUENCY RESPONSE											
Small Signal	Unity Gain	12.8	16		13.6	16		13.6	16		MHz
Full Power Bandwidth ³	$V_{\text{O}} = \pm 10 \text{ V}$ $R_{\text{LOAD}} = 500 \Omega$		1.75			1.75			1.75		MHz
Rise Time	10 V Step $C_{\text{LOAD}} = 100 \text{ pF}$ $R_{\text{LOAD}} = 500 \Omega$ to 0.01% to 0.1%		20			20			20		ns
Overshoot			20			20			20		%
Slew Rate		80	100		94	100		94	100		V/μs
Settling Time			350 250			350 250	500		350 250	500	ns ns
DIFFERENTIAL GAIN	$f = 4.4 \text{ MHz}$		0.04			0.04			0.04		%
DIFFERENTIAL PHASE	$f = 4.4 \text{ MHz}$		0.02			0.02			0.02		Degree
POWER SUPPLY											
Rated Performance	$V_{\text{S}} = \pm 5 \text{ to } \pm 15 \text{ V}$ T_{MIN} to T_{MAX}		±15			±15			±15		V
Operating Range		±4.75		±18	±4.75		±18	±4.75		±18	V
Rejection Ratio		88	110		95	113		88	110		dB
Quiescent Current			10	12		10 12			10 12		mA

NOTES

¹Input offset voltage specifications are guaranteed after five minutes of operation at $T_{\text{A}} = 25^{\circ}\text{C}$.

²Bias current specifications are guaranteed maximum at either input after five minutes of operation at $T_{\text{A}} = 25^{\circ}\text{C}$.

³FPBW = slew rate/2 π V peak.

⁴S grade $T_{\text{MIN}} - T_{\text{MAX}}$ are tested with automatic test equipment at $T_{\text{A}} = -55^{\circ}\text{C}$ and $T_{\text{A}} = +125^{\circ}\text{C}$.

All min and max specifications are guaranteed. Specifications shown in **boldface** are tested on all production units at final electrical test. Results from these tests are used to calculate outgoing quality levels.

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS¹

Supply Voltage	±18 V
Internal Power Dissipation ²	
Plastic Mini-DIP	1.6 W
CERDIP	1.4 W
16-Lead SOIC	1.5 W
Input Voltage	+V _S
Output Short-Circuit Duration	Indefinite
Differential Input Voltage	+V _S and -V _S
Storage Temperature Range	
Q	-65°C to +150°C
N, R	-65°C to +125°C
Lead Temperature Range (Soldering 60 sec)	300°C

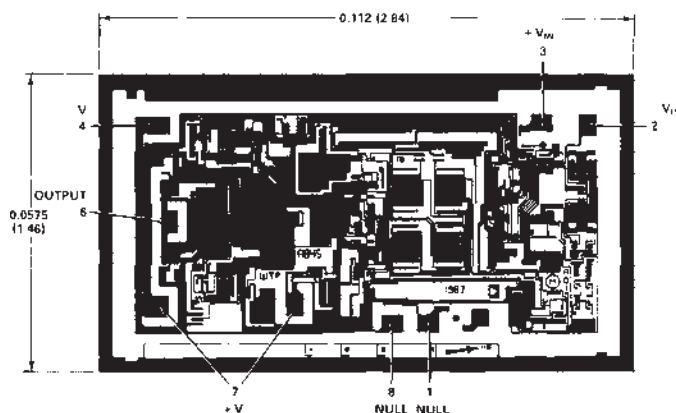
NOTES

¹Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

²Mini-DIP package: $\theta_{JA} = 100^\circ\text{C/W}$; CERDIP package: $\theta_{JA} = 110^\circ\text{C/W}$; SOIC package: $\theta_{JA} = 100^\circ\text{C/W}$.

METALIZATION PHOTOGRAPH

Dimensions shown in inches and (mm).
Contact factory for latest dimensions.



SUBSTRATE CONNECTED TO +V_S

ORDERING GUIDE

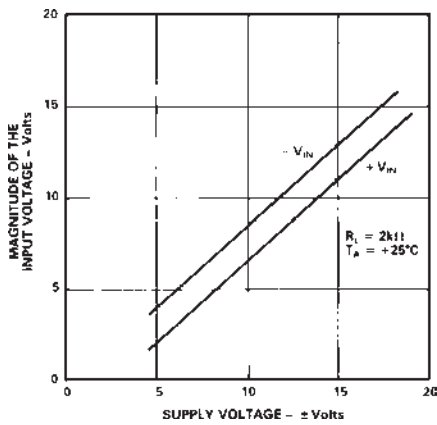
Model	Temperature Range	Package Description	Package Option ¹
AD845JN	0°C to 70°C	8-Lead PDIP	N-8
AD845KN	0°C to 70°C	8-Lead PDIP	N-8
AD845JR-16	0°C to 70°C	16-Lead SOIC	R-16
AD845JR-16-REEL	0°C to 70°C	Tape and Reel	R-16
AD845JR-16-REEL7	0°C to 70°C	Tape and Reel	R-16
AD845AQ	-40°C to +85°C	8-Lead CERDIP	Q-8
AD845BQ	-40°C to +85°C	8-Lead CERDIP	Q-8
AD845SQ	-55°C to +125°C	8-Lead CERDIP	Q-8
AD845SQ/883B	-55°C to +125°C	8-Lead CERDIP	Q-8
5962-8964501PA ²	-55°C to +125°C	8-Lead CERDIP	Q-8
AD845JCHIPS	0°C to 70°C	Die	

NOTES

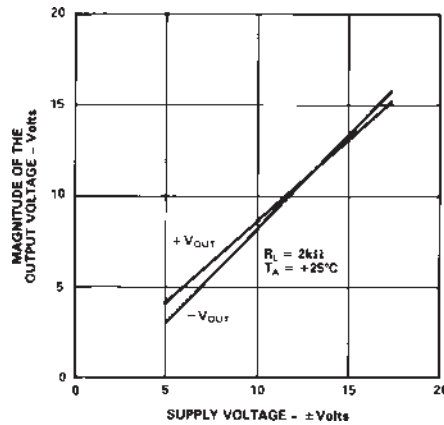
¹N = Plastic DIP; Q = CERDIP; R = Small Outline IC (SOIC).

²See military data sheet.

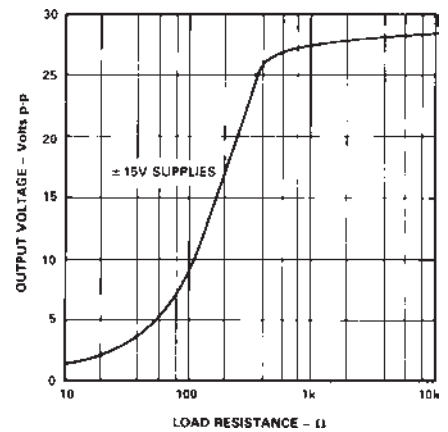
AD845—Typical Performance Characteristics



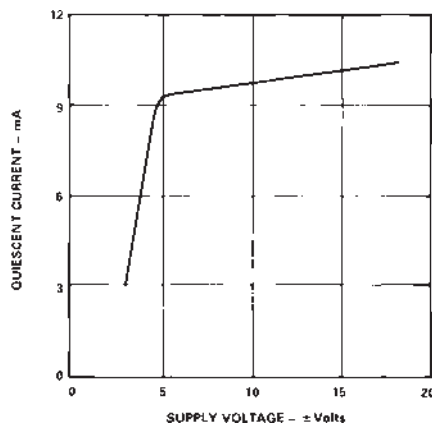
TPC 1. Input Voltage Swing vs. Supply Voltage



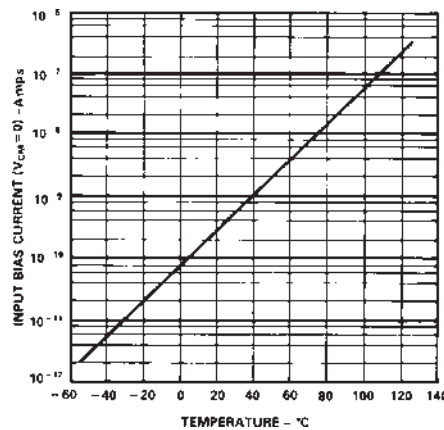
TPC 2. Output Voltage Swing vs. Supply Voltage



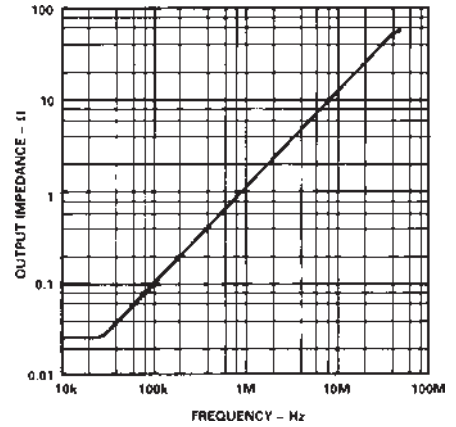
TPC 3. Output Voltage Swing vs. Resistive Load



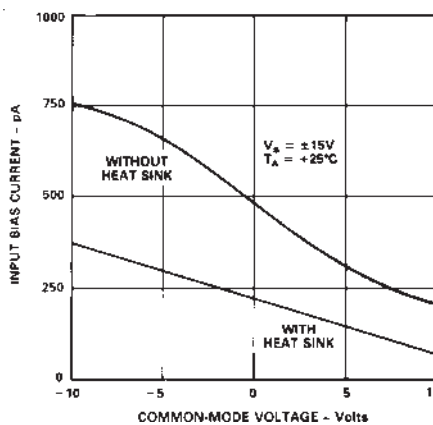
TPC 4. Quiescent Current vs. Supply Voltage



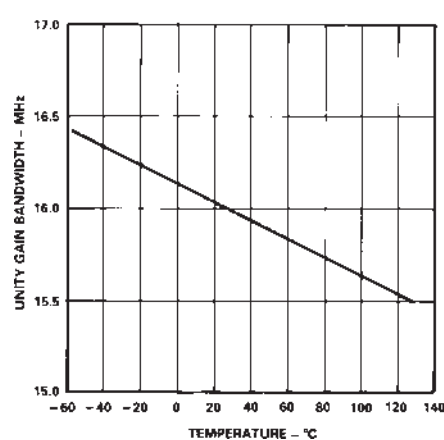
TPC 5. Input Bias Current vs. Temperature



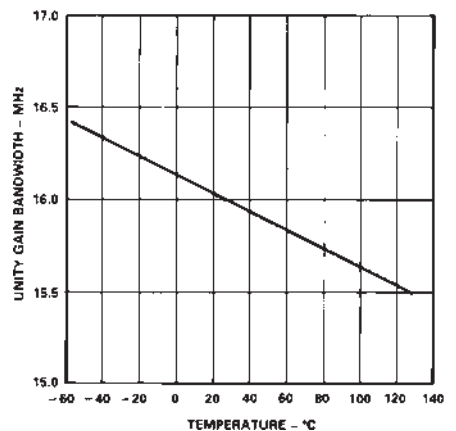
TPC 6. Magnitude of Output Impedance vs. Frequency



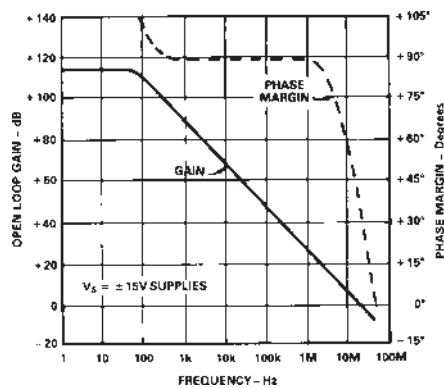
TPC 7. Input Bias Current vs. Common-Mode Voltage



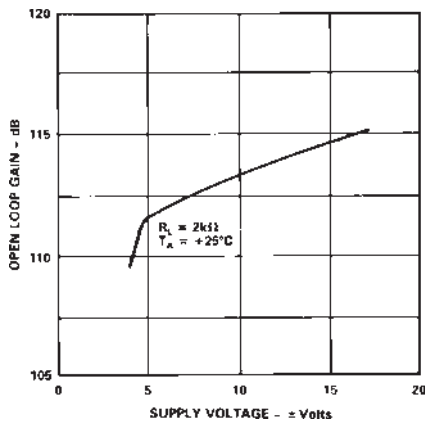
TPC 8. Short-Circuit Current Limit vs. Temperature



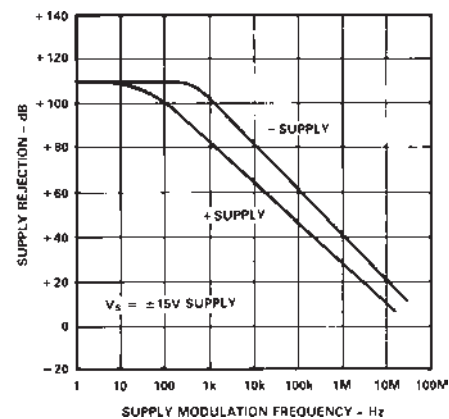
TPC 9. Unity-Gain Bandwidth vs. Temperature



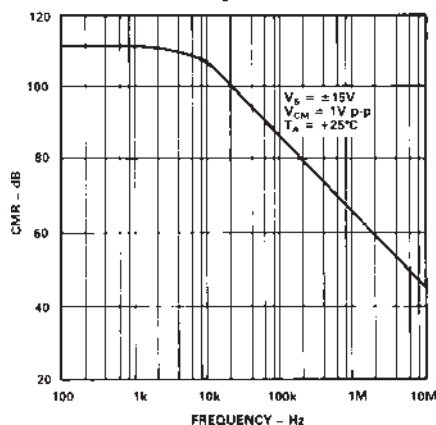
TPC 10. Open-Loop Gain and Phase Margin vs. Frequency



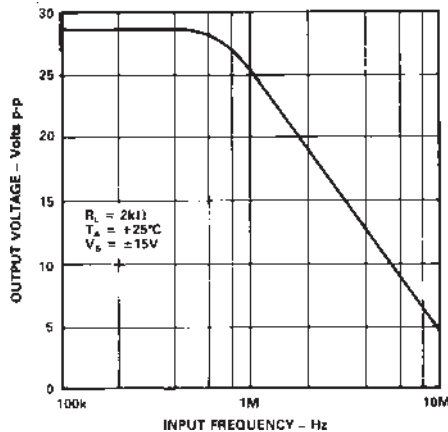
TPC 11. Open-Loop Gain vs. Supply Voltage



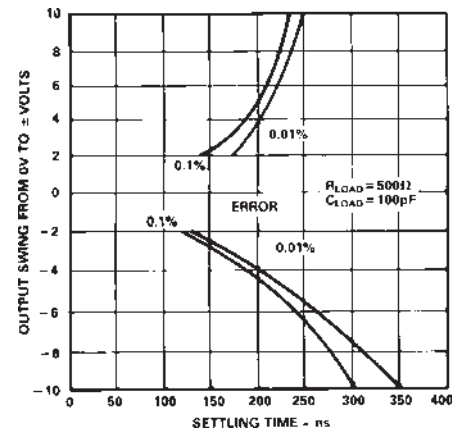
TPC 12. Power Supply Rejection vs. Frequency



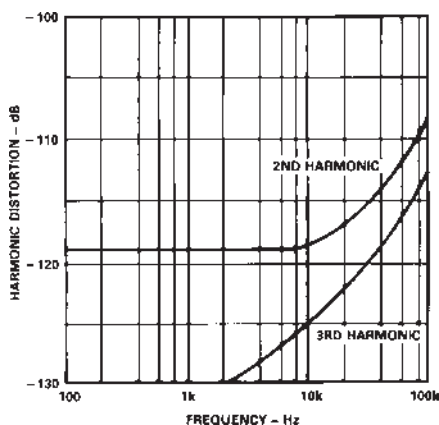
TPC 13. Common-Mode Rejection vs. Frequency



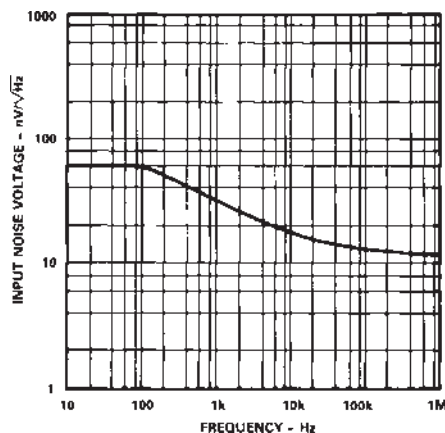
TPC 14. Large Signal Frequency Response



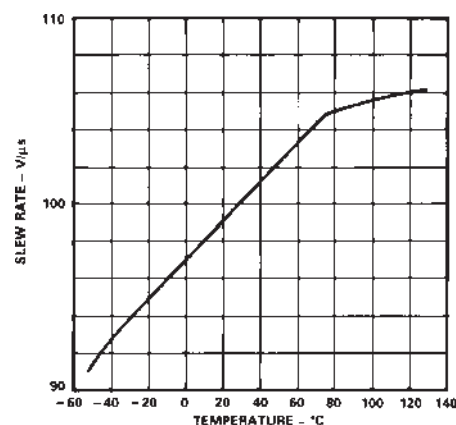
TPC 15. Output Swing and Error vs. Settling Time



TPC 16. Harmonic Distortion vs. Frequency

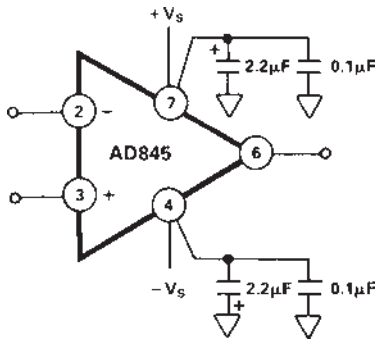


TPC 17. Input Noise Voltage Spectral Density

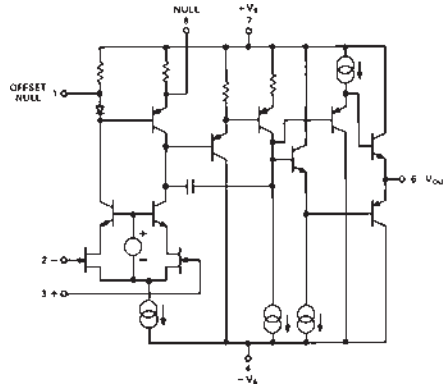


TPC 18. Slew Rate vs. Temperature

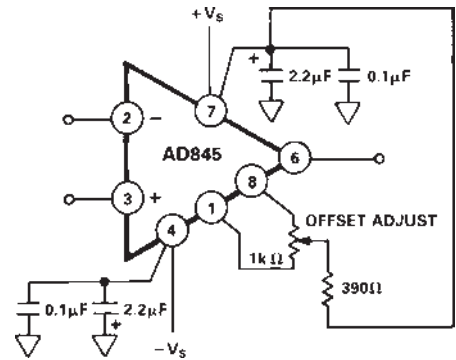
AD845



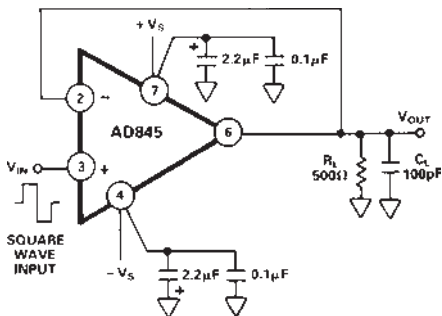
TPC 19. Recommended Power Supply Bypassing



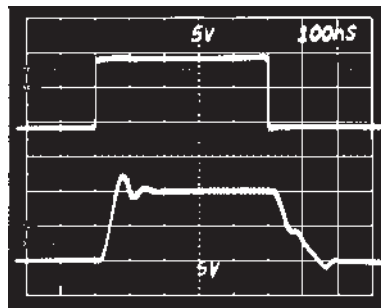
TPC 20. AD845 Simplified Schematic



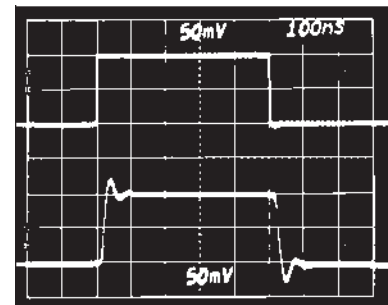
TPC 21. Offset Null Configuration



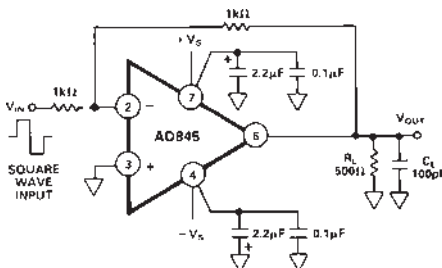
TPC 22. Unity Gain Follower



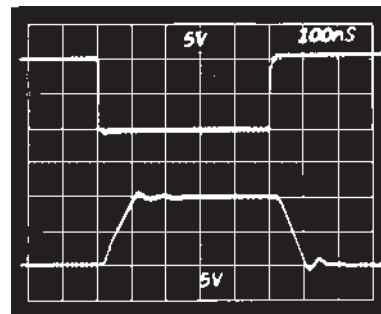
TPC 23. Unity Gain Follower Large Signal Pulse Response



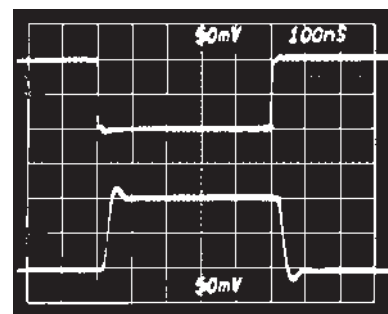
TPC 24. Unity Gain Follower Small Signal Pulse Response



TPC 25. Unity Gain Inverter



TPC 26. Unity Gain Inverter Large Signal Pulse Response



TPC 27. Unity Gain Inverter Small Signal Pulse Response

MEASURING AD845 SETTLING TIME

Figure 1 shows AD845 settling time performance. This measurement was accomplished by driving the amplifier in the unity gain inverting mode with a fast pulse generator. The input summing junction was measured using false nulling techniques. Settling time is defined as the interval of time from the application of an ideal step function input until the closed-loop amplifier output has entered and remains within a specified error band.

Components of settling time include:

- 1. Propagation time through the amplifier
- 2. Slewing time to approach the final output value
- 3. Recovery time from overload associated with the slewing
- 4. Linear settling to within a specified error band

These individual components can be seen easily in Figure 1. Settling time is extremely important in high speed applications where the current output of a DAC must be converted to a voltage. When driving a 500 Ω load in parallel with a 100 pF capacitor, the AD845 settles to 0.1% in 250 ns and to 0.01% in 310 ns.

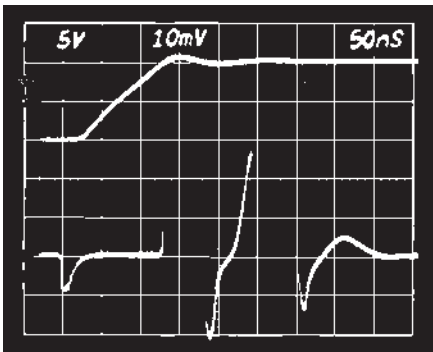


Figure 1. Settling Characteristics 0 V to 10 V Step
Upper Trace: Output of AD845 Under Test (5 V/Div)
Lower Trace: Error Voltage (1 mV/Div)

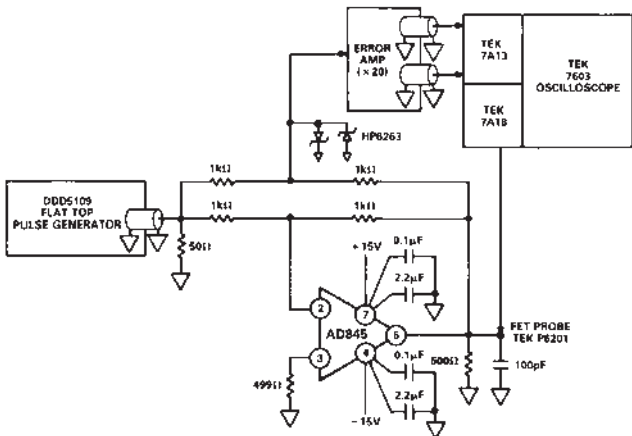


Figure 2. Settling Time Test Circuit

A HIGH SPEED INSTRUMENTATION AMP

The 3-op amp instrumentation amplifier circuit shown in Figure 3 can provide a range of gains from unity up to 1000 and higher. The instrumentation amplifier configuration features high common-mode rejection, balanced differential inputs, and

stable, accurately defined gain. Low input bias currents and fast settling are achieved with the FET input AD845.

Most monolithic instrumentation amplifiers do not have the high frequency performance of the circuit in Figure 3. The circuit bandwidth is 10.9 MHz at a gain of 1 and 8.8 MHz at a gain of 10; settling time for the entire circuit is 900 ns to 0.01% for a 10 V step (Gain = 10).

The capacitors employed in this circuit greatly improve the amplifier's settling time and phase margin.

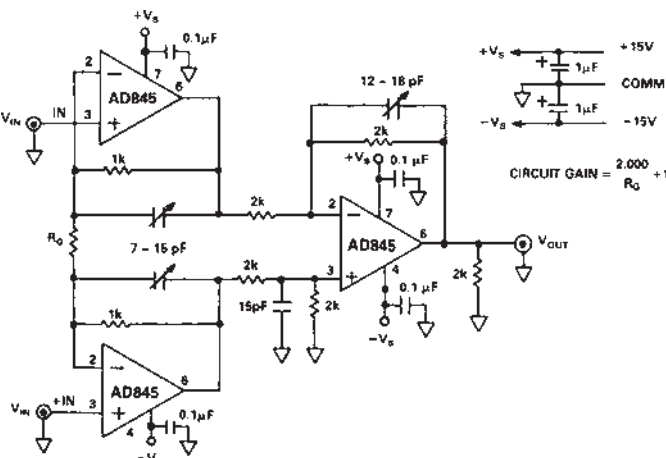


Figure 3. High Performance, High Speed Instrumentation Amplifier

Table I. Performance Summary for the 3-Op Amp Instrumentation Amplifier Circuit

3-Op Amp In-Amp			
Gain	R _G	Small Signal Bandwidth	Settling Time to 0.01%
1	Open	10.9 MHz	500 ns
2	2 kΩ	8.8 MHz	500 ns
10	226 Ω	2.6 MHz	900 ns
100	20 Ω	290 kHz	7.5 μs

Note: Resistors around the amplifiers' input pins need to be small enough in value so that the RC time constant they form, with stray circuit capacitance, does not reduce circuit bandwidth.

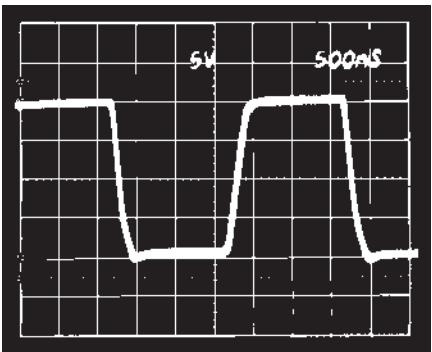


Figure 4. The Pulse Response of the 3-Op Amp Instrumentation Amplifier. Gain = 1, Horizontal Scale = 0.5 ms/Div and Vertical Scale = 5 V/Div.

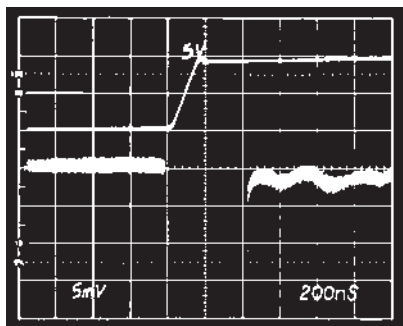


Figure 5. Settling Time of the 3-Op Amp Instrumentation Amplifier. Horizontal Scale is 200 ns/Div, Vertical Scale, Positive Pulse Input is 5 V/Div and Output Settling is 1 mV/Div.

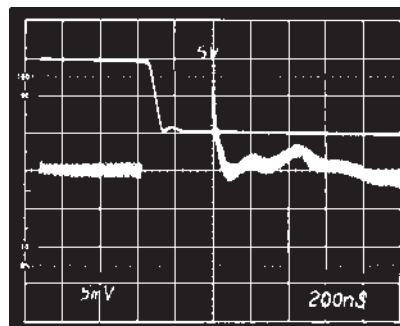


Figure 6. Settling Time of the Three Op Amp Instrumentation Amplifier. Horizontal Scale: 200 ns/Div; Vertical Scale, Negative Pulse Input: 5 V/Div; Output Settling: 1 mV/Div.

DRIVING THE ANALOG INPUT OF AN A/D CONVERTER

An op amp driving the analog input of an A/D converter, such as that shown in Figure 7, must be capable of maintaining a constant output voltage under dynamically changing load conditions. In successive approximation converters, the input current is compared to a series of switched trial currents. The comparison point is diode clamped but may deviate several hundred millivolts, resulting in high frequency modulation of A/D input current. The output impedance of a feedback amplifier is made artificially low by the loop gain. At high frequencies, where the loop gain is low, the amplifier output impedance can approach its open-loop value. Most IC amplifiers exhibit a minimum open-loop output impedance of 25 Ω due to current limiting resistors. A few hundred microamps reflected from the change in converter loading can introduce errors in instantaneous input voltage. If the A/D conversion speed is not excessive and the bandwidth of the amplifier is sufficient, the amplifier's output will return to the nominal value before the converter makes its comparison. However, many amplifiers have relatively narrow bandwidth, yielding slow recovery from output transients. The

AD845 is ideally suited to drive high resolution A/D converters with 5 μ s or longer conversion times since it offers both wide bandwidth and high open-loop gain.

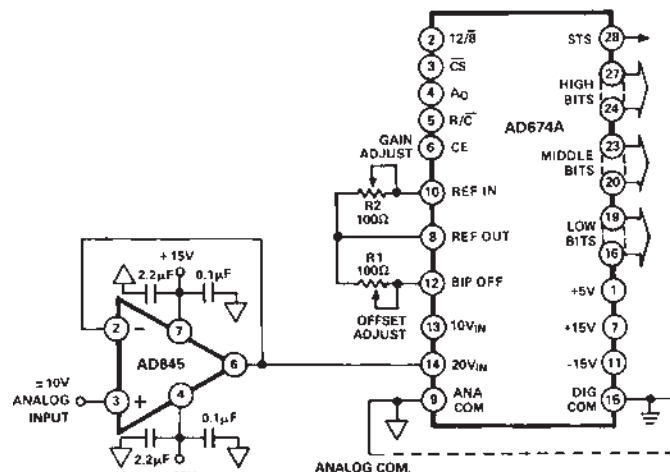
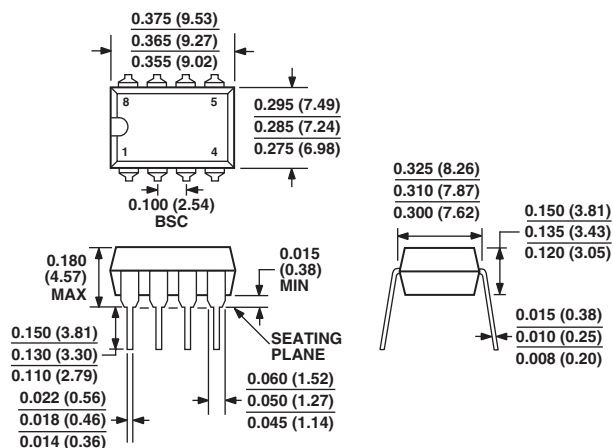


Figure 7. AD845 As ADC Unity Gain Buffer

OUTLINE DIMENSIONS

8-Lead Plastic Dual In-Line Package [PDIP]
(N-8)

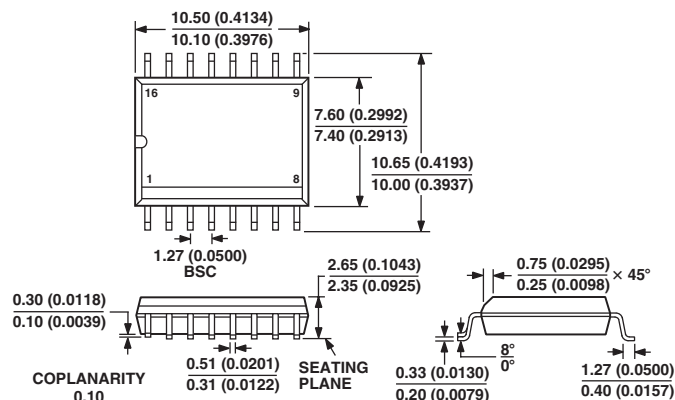
Dimensions shown in inches and (millimeters)



COMPLIANT TO JEDEC STANDARDS MO-095AA
 CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETER DIMENSIONS
 (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR
 REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN

16-Lead Standard Small Outline Package [SOIC]
Wide Body
(R-16)

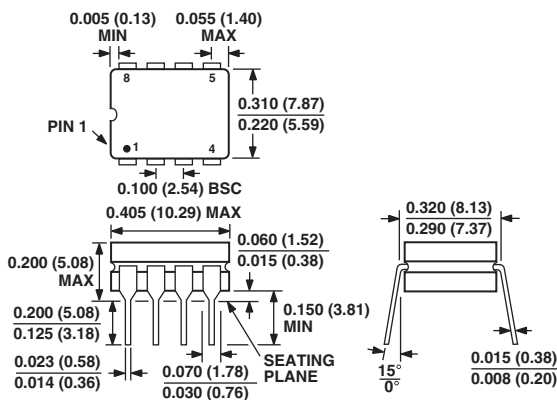
Dimensions shown in millimeters and (inches)



COMPLIANT TO JEDEC STANDARDS MS-013AA
 CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
 (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
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8-Lead Ceramic Dual In-Line Package [CERDIP]
(Q-8)

Dimensions shown in inches and (millimeters)



CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETERS DIMENSIONS
 (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR
 REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN

AD845

Revision History

Location	Page
10/03—Data Sheet changed from REV. D to REV. E.	
Renumbered figures and TPCs	Universal
Updated OUTLINE DIMENSIONS	9

